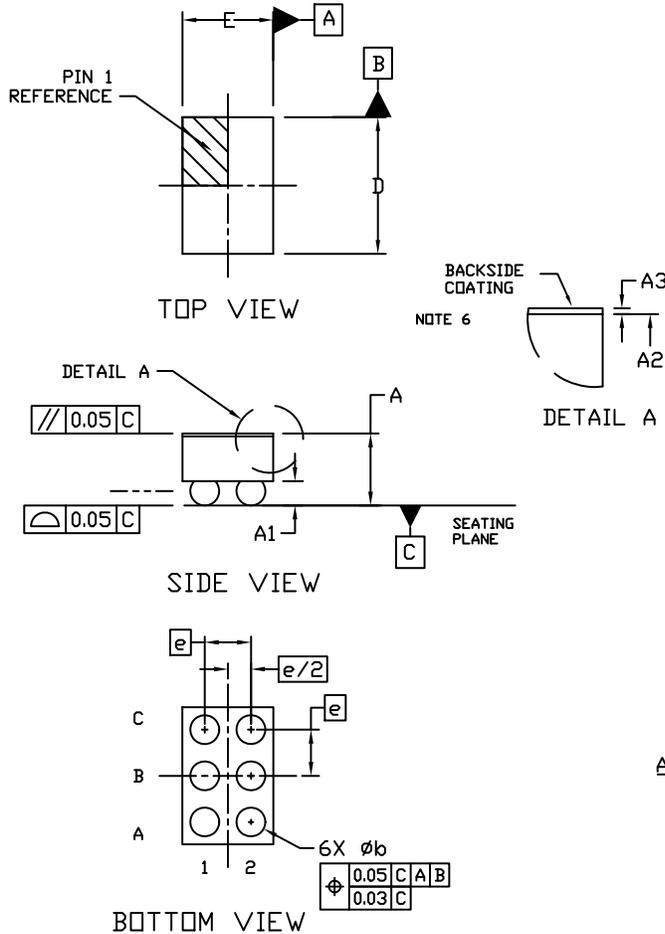


**WLCSP6, 1.1888x0.788x0.625**  
CASE 567YQ  
ISSUE O

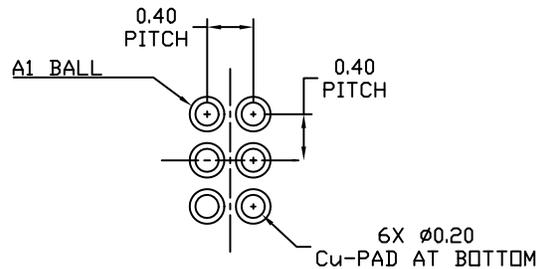
DATE 12 NOV 2019



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE CONTACT BALLS.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE CONTACT BALLS.
5. DIMENSION b IS MEASURED AT THE MAXIMUM CONTACT BALL DIAMETER PARALLEL TO DATUM C.
6. BACKSIDE COATING IS OPTIONAL.

DIM	MILLIMETERS	
	MIN.	MAX.
A	---	0.625
A1	0.10	0.17
A2	0.35 REF	
A3	0.025 REF	
b	0.20	0.30
D	1.156	1.22
E	0.756	0.82
e	0.40 BSC	



**RECOMMENDED MOUNTING FOOTPRINT\***  
(NSMD PAD TYPE)

\* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

**GENERIC MARKING DIAGRAM\***



- X = Specific Device Code
- Y = Year
- W = Work Week

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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<b>DESCRIPTION:</b>	<b>WLCSP6, 1.1888x0.788x0.625</b>	<b>PAGE 1 OF 1</b>

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